

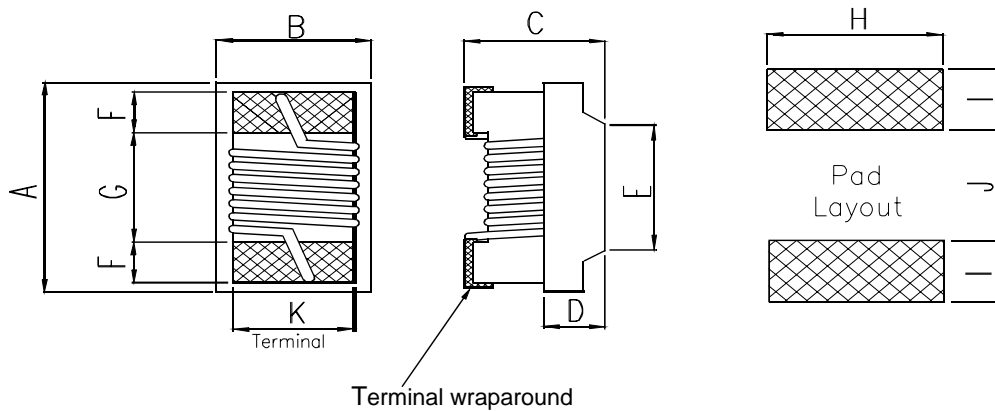
Specification For Approval

Wire-Wound Chip Inductor 0805 (201209Q) Series

Part Number	Inductance nH	Percent Tolerance	Q Min	SRF Min MHz	R _{DC} Max Ohms	I _{DC} Max mA
BCCWH-201209Q-2N5	2.5 @ 250MHz	10,5	80 @ 1500MHz	6000	0.020	1600
BCCWH-201209Q-5N6	5.6 @ 250MHz	10,5	98 @ 1500MHz	6000	0.035	1600
BCCWH-201209Q-6N2	6.2 @ 250MHz	10,5	88 @ 1000MHz	4750	0.035	1600
BCCWH-201209Q-6N8	6.8 @ 250MHz	10,5	80 @ 1000MHz	4400	0.035	1600
BCCWH-201209Q-8N2	8.2 @ 250MHz	10,5	75 @ 1000MHz	3000	0.075	1000
BCCWH-201209Q-10N	10 @ 250MHz	10,5	80 @ 1000MHz	3000	0.060	1600
BCCWH-201209Q-12N	12 @ 250MHz	10,5	80 @ 1000MHz	3000	0.045	1600
BCCWH-201209Q-15N	15 @ 250MHz	10,5,2	80 @ 1000MHz	2800	0.100	1200
BCCWH-201209Q-16N	16 @ 250MHz	10,5,2	72 @ 500MHz	2950	0.060	1500
BCCWH-201209Q-18N	18 @ 250MHz	10,5,2	75 @ 500MHz	2550	0.060	1400
BCCWH-201209Q-20N	20 @ 250MHz	10,5,2	70 @ 500MHz	2050	0.055	1400
BCCWH-201209Q-22N	22 @ 250MHz	10,5,2	80 @ 500MHz	2000	0.100	1200
BCCWH-201209Q-27N	27 @ 250MHz	10,5,2	75 @ 500MHz	2000	0.070	1300
BCCWH-201209Q-30N	30 @ 250MHz	10,5,2	65 @ 500MHz	1950	0.095	1200
BCCWH-201209Q-39N	39 @ 250MHz	10,5,2	65 @ 500MHz	1600	0.110	1100
BCCWH-201209Q-48N	48 @ 200MHz	10,5,2	65 @ 500MHz	1400	0.095	1200
BCCWH-201209Q-51N	51 @ 200MHz	10,5,2	65 @ 500MHz	1400	0.120	1000

Working Temperature Range : -40 °C ~ 125 °C

Shape & Dimension



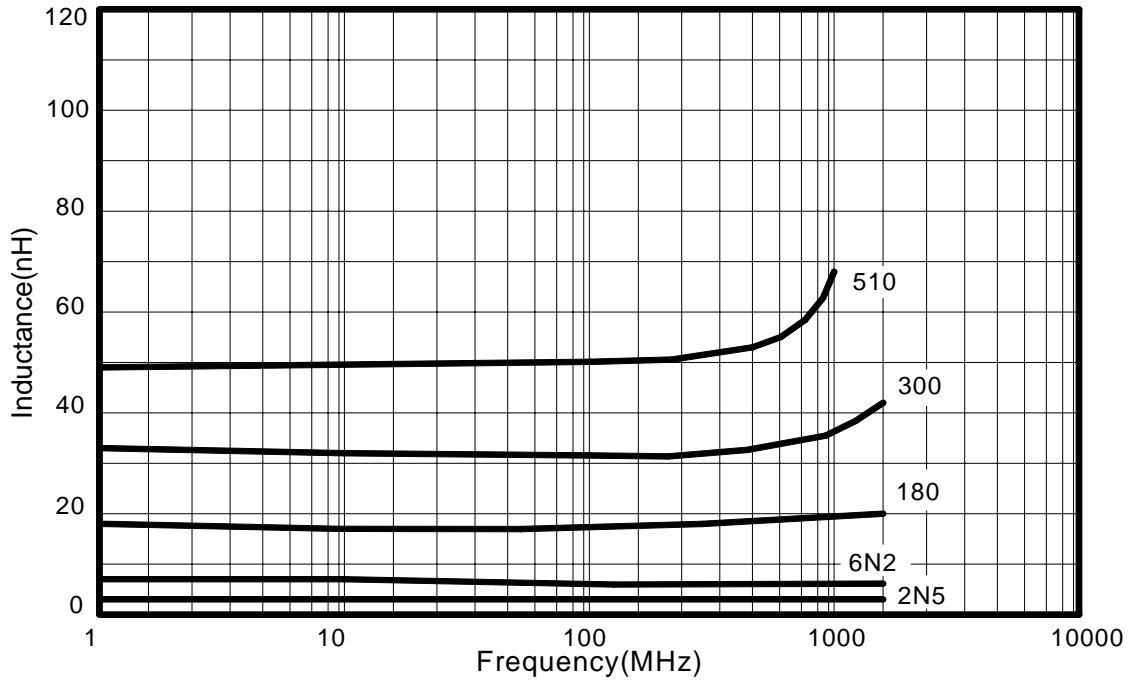
	A		B		C		D Ref.	E Ref.	F	G	H	I	J	K
	Max.	Ref	Max	Ref	Max	Ref								
inch	0.09	0.083	0.068	0.065	0.060	0.055	0.02	0.050	0.018	0.040	0.070	0.040	0.030	0.050
mm	2.29	2.10	1.73	1.65	1.52	1.40	0.51	1.27	0.44	1.02	1.78	1.02	0.76	1.27

Parts/Reel: 7" 2,000PCS

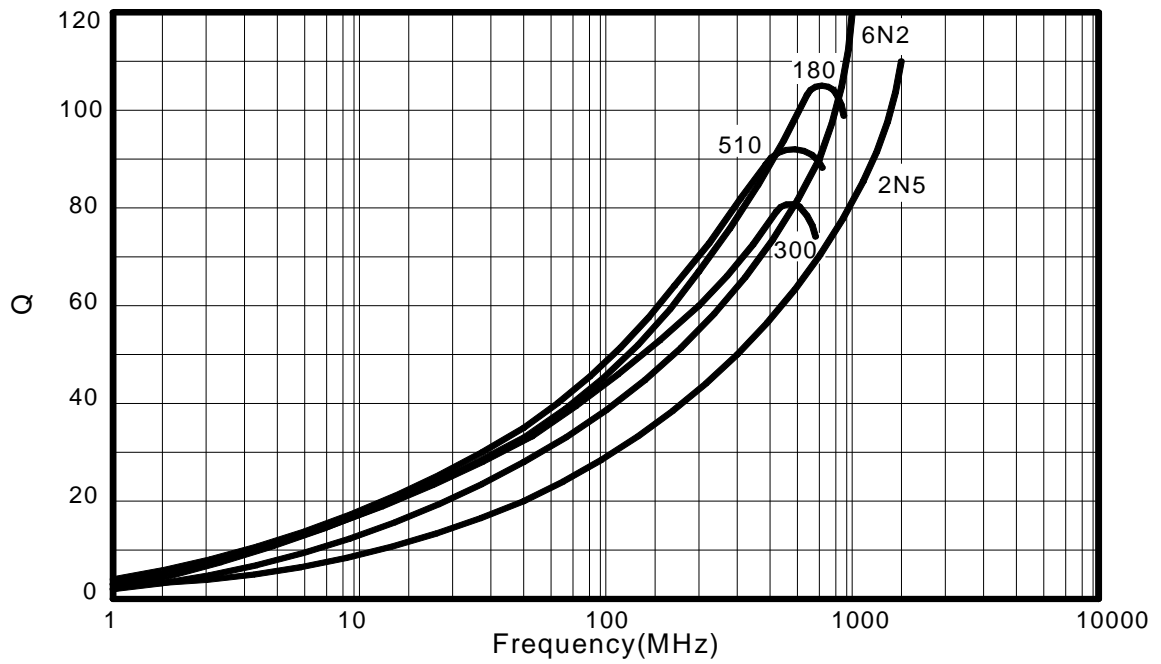
Tape Width: 8mm

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TYPICAL L vs FREQUENCY



TYPICAL Q vs FREQUENCY



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TEST ITEMS	SPECIFICATIONS	TEST CONDITIONS / TEST METHODS
*ELECTRICAL PERFORMANCE TEST		
INDUCTANCE	REFER TO STANDARD ELECTRICAL CHARACTERISTIC LIST	HP 4291B
Q		HP 4291B
SRF		HP 8753D
DC RESISTANCE R _{DC}		Micro-Ohmmeter (GOM-801G)
RATED CURRENT IDC		APPLIED THE CURRENT TO COILS, THE INDUCTANCE CHANGE SHOULD BE LESS THAN 10% TO INITIAL VALUE
OVER LOAD TEST	AFTER TEST, INDUCTORS SHALL BE NO EVIDENCE OF ELECTRICAL AND MECHANICAL DAMAGE	APPLIED 2 TIMES OF RATED ALLOWED DC CURRENT TO INDUCTOR FOR A PERIOD OF 5 MINUTE
WITHSTANDING VOITAGE TEST	1.AFTER TEST, INDUCTORS SHALL BE NO EVIDENCE OF ELECTRICAL AND MECHANICAL DAMAGE	AC VOLTAGE OF 500 VAC APPLIED BETWEEN INDLUICTORS TERMINAL AND CASE FOR 1 MINUTE
INSULATION RESISTANCE TEST	1000 MOHM MIN.	100 VDC APPLIED BETWEEN INDUCTOR TERMINAL AND CASE
*MECHANICAL PERFORMANCE TEST		
VIBARATION TEST (LOW FREQUENCY)	1.INDUCTORS SHOULD HAVE NO EVIDENCE OF ELECTRICAL AND MECHANICAL DAMAGE 2.INDUCTANCE SHOULD NOT CHANGE MORE THAN±5% 3.Q SHOULD NOT CHANGE MORE THAN±10%	1. AMPLITUDE: 1.5m/m 2. FREQUENCY: 10-55-10 Hz(1min) 3. DIRECTION: X, Y, Z 4. DURATION: 2 HRS/X, Y, Z
RESISTANCE TO SOLDERING TEST		INDUCTORS SHOULD BE REF.LOW TO A .PC BOARD. USING 63Sn/37Pb SOLDER PASTE.SOLDER PROCESS SHOULD BE 230 FOR 20±2 SECONDS AND 260 FOR 5±2 SECONDS.
COMPONENT ADHESIONN (PUSH TEST)	1 lbs. FOR 0402 2 lbs. FOR 0603 4 lbs. FOR THE REST	THE DEVICE SHOULD BE REF.LOW SOLDERED (232 ±5 FOR 10 SECONDS) TO A TINNED COPPER SUBSTRATE. A DYNOMETER FORCE GAUGE SHOULD BE APPLIED TO THE SIDE OF THE COMPONENT. THE DEVICE MUST WITHSTAND A MINIMUM FORCE OF 2 OR 4 POUNDS WITHOUT A FAILURE OF THE TERMINATION ATTACHED TO COMPONENT.
DROP TEST	AFTER TEST ,THE CHIP INDUCTOR DON'T FELL OR BROKE ON THE P.C BOARD.	DROP 1 TIME FOR EACH FACE AND 1 TIME FOR EACH CORNER.TOTAL DROP 10 TIMES. DROP HEIGHT :100 CM DROP WEIGHT :125 g
SOLDERABILITY TEST	THE TERMINAL SHOULD AT LEAST BE 90% COVERED WITH SOLDER	AFTER FLUXING(ALPHA 100 OR EQUIV), INDUCTOR SHALL BE DIPPED IN A MELTED SOLDER BATH AT 232 ±5 FOR 5 SECONDS.

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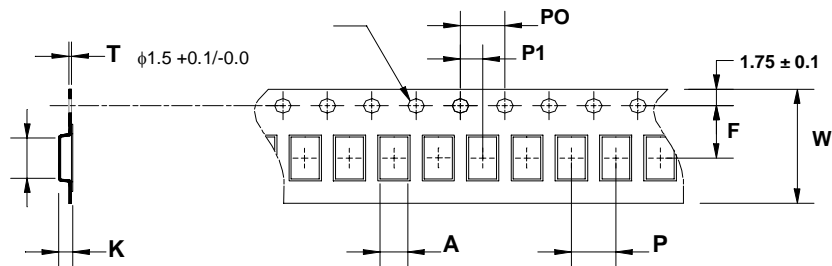
SOLDERABILITY TEST	THE TERMINAL SHOULD HAVE AT LEAST 90% COVERED WITH SOLDER	AFTER FLUXING (ALPHA 100 OR EQUIV), INDUCTOR SHALL BE DIPPED IN A MELTED SOLDER BATH AT 232 ±5 FOR 5 SECONDS.
RESISTANCE TO SOLVENT TEST	THERE SHALL BE NO CASE OF DEFORMATION CHANGE IN APPEARANCE OR OBLITERATION OF MARKING.	MIL-STD202F, METHOD 215D
*CLIMATIC TEST		
TEMPERATURE CHARACTERISTIC	1.INDUCTORSSHAL HAVE NO EVIDENCE OF ELECTRICAL AND MECHANICAL DAMAGE 2..INDUCTANCE SHALL NOT CHANGE MORE THAN ±10% 3. SHALL NOT CHANGE MORE THAN ±20%	-40 ~ +125
HUMIDITY TEST		1. TEMP : 40 ± 2 2. R.H. : 90 – 95% 3. TIME : 96 ±2 HOURS
LOW TEMPERATURE STORAGE TEST		1. TEMP : -40 ±2 2. TIME : 48 ±2 HOURS 3.INDUCTORS ARE TO BE TESTED AFTER 1HOUR AT ROOM TEMPERATURE.
THERMAL SHOCK TEST		<p>TOTAL : 5 CYCLES</p>
HIGH TEMPERATURE STORAGE TEST		1. TEMP : 125 ± 2 2. TIME : 48 ± 2 HOURS 3.INDUCTORS ARE TO BE TESTED AFTER 1HOUR AT ROOM TEMPERATURE.
HIGH TEMPERATURE LOAD LIFE TEST		1. TEMP : 85 ± 2 2. TIME : 1000 ± 12 HOURS 3. LOAD : ALLOWED DC CURRENT
HUMIDITY LOAD LIFE	1. TEMP : 40 ± 2 2. R.H. : 90 – 95% 3. TIME : 1000 ± 12 HOURS 4. LOAD : ALLOWED DC CURRENT	
NOTE : UNLESS OTHERWISE SPECIFIED, ALLOW THE SPECIMEN TO STAND AT ROOM TEMPERATURE FOR 1 HOUR OR MORE BUT NOT MORE THAN 2 HOURS, MEASURE THE ELECTRICAL AND MECHANICAL PERFORMANCES.		

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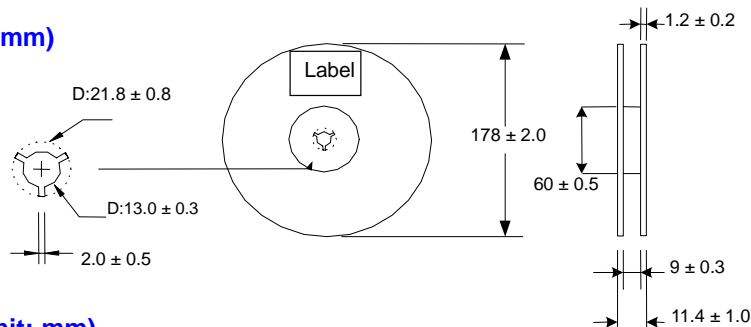
Package Specification.

Tape Dimensions (Unit:mm)

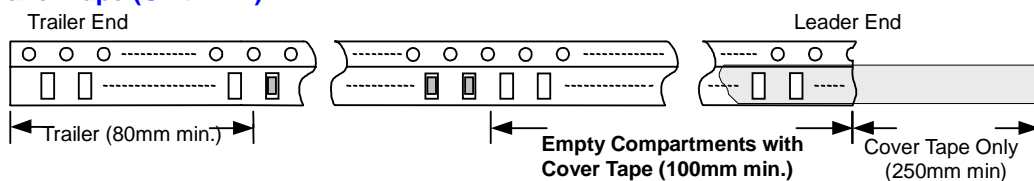


	Tape Dimensions (mm)									Parts (pcs)
	A	B	K	T	F	P	P0	P1	W	7"
201209	1.85	2.30	1.45	0.23	3.5	4	4	2	8	2000

Reel Dimensions (Unit: mm)



Leader / Trailer Tape (Unit: mm)



Peel-off Force

Peel-off force should be in the range of 0.1~0.7N at a peel-off speed of 300±10 mm/min

